

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A mold die comprising a first die having a recess of a predetermined form and a second flat die, said first die to be disposed on a surface of a wiring board which has a plurality of openings including a bonding opening and a semiconductor chip mounted on said surface via an elastic material, and said second die to be disposed on a back of said surface of said wiring board on which said semiconductor chip is mounted, for sealing with an insulating resin a periphery of said semiconductor chip and at least ~~one of said openings~~ bonding opening of said wiring board, wherein

said second die comprises a protrusion disposed around an area overlapping said bonding opening to be sealed with said insulating resin.

2. (Currently Amended) A method for manufacturing a semiconductor device by sealing, by transfer mold processing using a die, a semiconductor chip mounted on a wiring board via an elastic material, which board includes an insulating substrate with a plurality of openings including a bonding opening thereon on which a conductive pattern is formed, and by sealing at least ~~one of said openings~~ bonding opening, wherein

a die having a protrusion disposed around an area overlapping said bonding opening to be sealed is used for a back die member to be placed in contact with the surface of said wiring board on the opposite side on which said semiconductor chip is mounted.

3. (New) The method according to claim 2, wherein said wiring board has a conductive pattern electrically connected to an external electrode of said semiconductor chip in said bonding opening.

4. (New) A mold die according to claim 1, wherein said wiring board has a conductive pattern electrically connected to an external electrode of said semiconductor chip in said bonding opening.